

# Stripper Series

## Uni-body Design Concept

Foot-print outstanding (ref 0.8m\*0.8m)

## Uniform Chamber Center Pump-down

Better process performance

## Uniform Gas Feed-in

Tuned as a preset parameter dependently

## Configurable Plasma Discharge Gap

Tuned as a preset parameter dependently

## Cost or Performance Orientation

RF, Pump, Values etc. depending on requirements

## Sample Handling

Open-Load



| Specification                 | Parameters  |
|-------------------------------|---|
| Wafer Size Range              | 4,6,8,12 inch or multi-wafers optional  |
| Etching Materials             | Organics (PR/PMMA/PS nanosphere etc.),<br>2D Materials (MoS2/BN/Graphene etc.),<br>Failure Analysis, etc. |
| Vacuum                        | Mechanical pump   |
| RF Power                      | Full range 300-1000W, optional  |
| Gas System                    | 2 lines(Standard) or customized   |
| Wafer Cooling                 | Water cooling   |
| Wafer Stage Temperature Range | From 5°C to 200°C, optional   |
| Non-Uniformity                | Less than ±5%(Edge Exclusion)   |